

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings of claims in the application:

**Listing of Claims:**

- 1                   1.       (Currently amended): A semiconductor laser module having a  
2 semiconductor laser element, a submount bonded to this semiconductor laser element with a  
3 solder layer in-between and thereby mounted with it, and a base mounted with this submount  
4 with another solder layer in-between, wherein:  
5                     $T/W \geq 0.15$  holds, where W is a width of said submount in a direction orthogonal  
6 to an optical axis of said semiconductor laser element and T is a thickness of said submount, and  
7                    the main constituent material of said semiconductor laser element is indium-  
8 phosphorus, the member constituting said submount is aluminum nitride, and the main  
9 constituent material of said base is copper-tungsten.

2-6.   (Canceled)